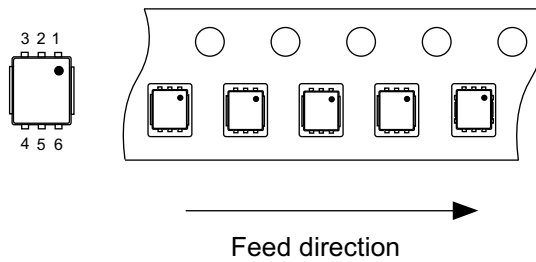
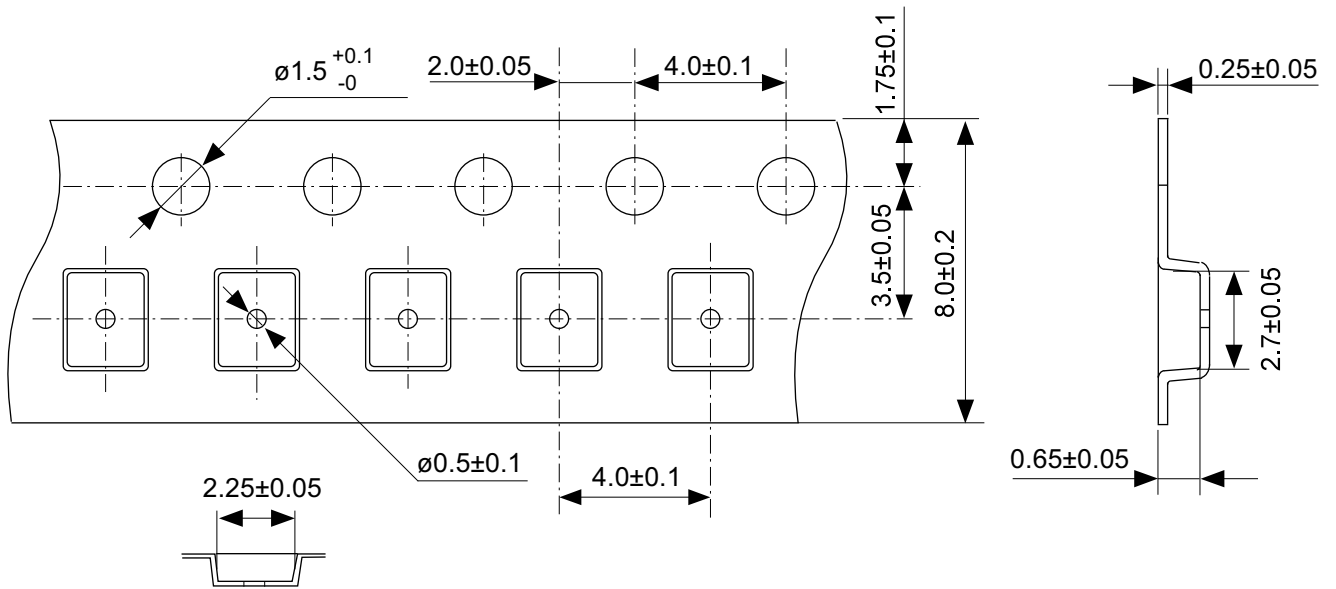


※ The heat sink of back side has different electric potential depending on the product.  
 Confirm specifications of each product.  
 Do not use it as the function of electrode.

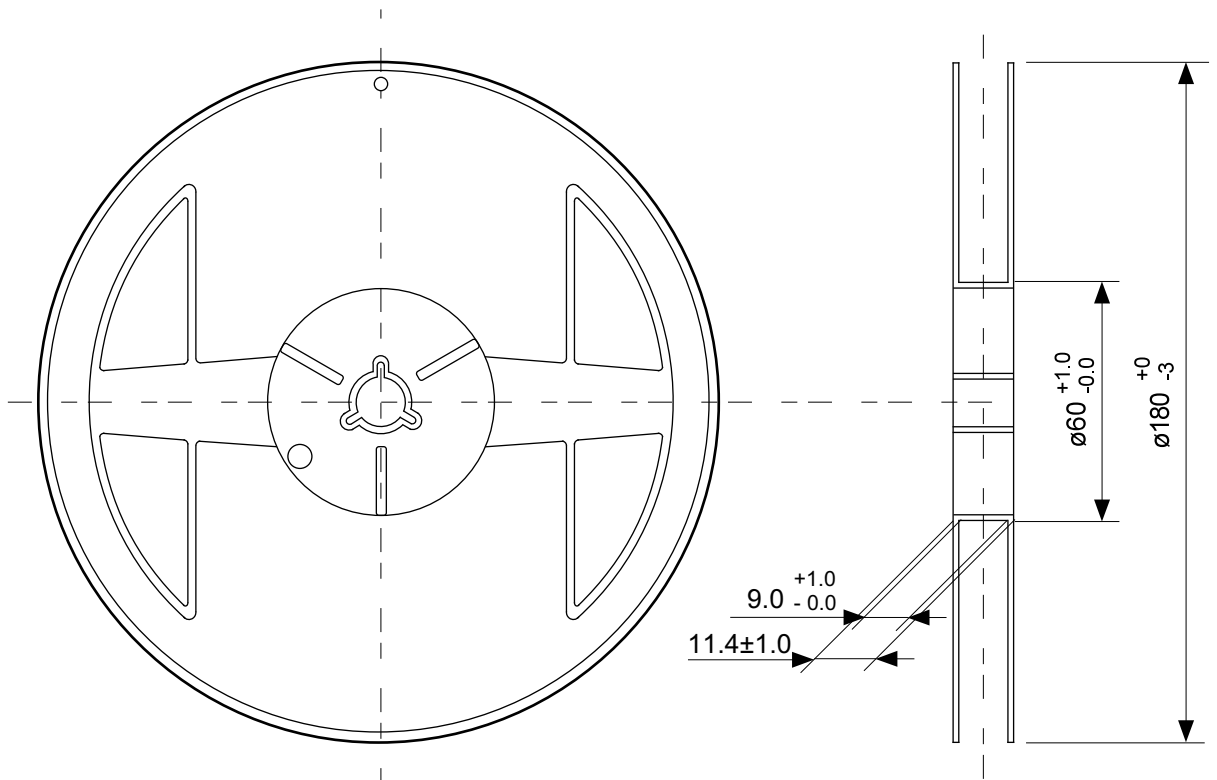
No. PJ006-B-P-SD-1.0

TITLE	HSNT-6-C-PKG Dimensions
No.	PJ006-B-P-SD-1.0
ANGLE	
UNIT	mm
<b>ABLIC Inc.</b>	

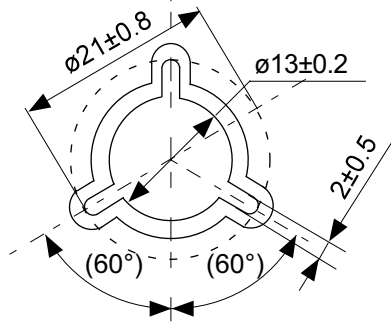


No. PJ006-B-C-SD-1.0

TITLE	HSNT-6-C-Carrier Tape
No.	PJ006-B-C-SD-1.0
ANGLE	
UNIT	mm
<b>ABLIC Inc.</b>	

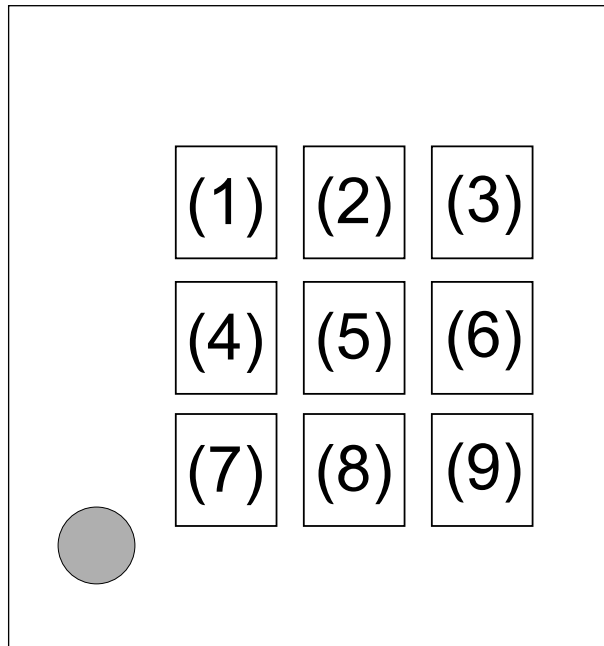


Enlarged drawing in the central part



No. PJ006-B-R-SD-1.0

TITLE	HSNT-6-C-Reel		
No.	PJ006-B-R-SD-1.0		
ANGLE		QTY.	5,000
UNIT	mm		
<b>ABLIC Inc.</b>			



△  
PKG PIN#1

(1) to (4) : Product code

(5) : Year of assembly

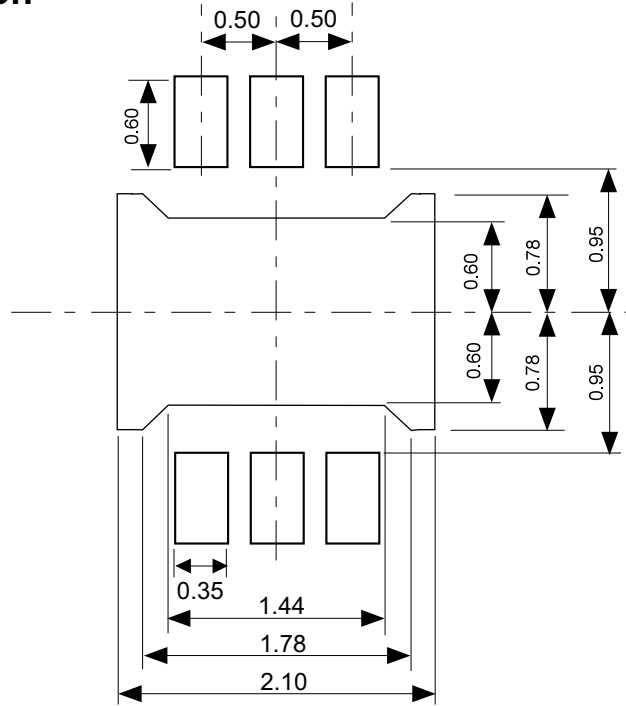
(6) : Month of assembly

(7) to (9) : Lot No.

No. PJ006-B-M-SD-1.0

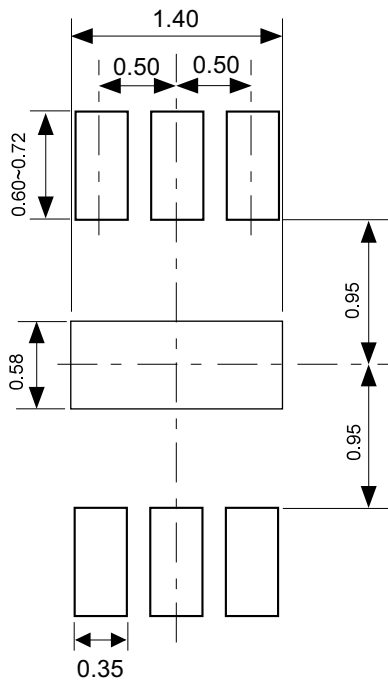
TITLE	HSNT-6-C-Markings		
No.	PJ006-B-M-SD-1.0		
ANGLE			
UNIT		TYPE	LASER
<b>ABLIC Inc.</b>			

## Land Recommendation



Caution It is recommended to solder the heat sink to a board in order to ensure the heat radiation.  
 注意 放熱性を確保する為に、PKGの裏面放熱板(ヒートシンク)を基板に半田付けする事を推奨いたします。

## Stencil Opening



No. PJ006-B-LM-SD-1.0

Caution ① Mask aperture ratio of the lead mounting part is 100~120%.  
 ② Mask aperture ratio of the heat sink mounting part is 30%.  
 ③ Mask thickness: t0.12 mm  
 ④ Reflow atmosphere: Nitrogen atmosphere is recommended.  
 (Oxygen concentration: 1000ppm or less)

注意 ①リード実装部のマスク開口率は100~120%です。  
 ②放熱板実装のマスク開口率は30%です。  
 ③マスク厚み : t0.12 mm  
 ④リフロー雰囲気・窒素雰囲気(酸素濃度1000ppm以下) 推奨

TITLE	HSNT-6-C -Land & Stencil Opening
No.	PJ006-B-LM-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	